

PATENT

Docket No.: M4065.0127/P127-A

21A
1/7/01
M. P. Hedges

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kie Y. Ahn et al.

Serial No.: (Not Yet Assigned - Divisional
of Serial No. 09/241,061)

Group Art Unit: 2815

Filed: Concurrently Herewith

Examiner: S. Clark

For: SILICON MULTI-CHIP MODULE
PACKAGING WITH
INTEGRATED PASSIVE
COMPONENTS AND METHOD
OF MAKING

Assistant Commissioner for Patents
Washington, D.C. 20231

FIRST PRELIMINARY AMENDMENT

Dear Sir:

Prior to examination on the merits, please amend the above-identified U.S.
patent application as follows:

In the Specification:

Page 1, line 3, before "Field of the Invention" please add -- This application is a
divisional application of application Ser. No. 09/241,061 filed on February 1, 1999, now
U.S. Patent No. , which is hereby incorporated by reference. --